CERAMIC / HERMETIC

data sheet

CLGA

Ceramic Land Grid Array Package (CLGA)

This surface mount package is the same as the Ceramic Pin Grid Array, except that the pins are replaced by pads. This package consists of a co-fired ceramic base that has a matrix of pads on the bottom of the base. The lid for this package can be either ceramic "frit sealed" or metal "solder sealed". This IC package technology allows application and design engineers to maximize the performance characteristics of semiconductors (silicon & GaAs). CLGAs are designed for low inductance, enhanced thermal operation and capability. Custom performance enhancements are available for significant improvements in electrical response demanded by advancing electronics.

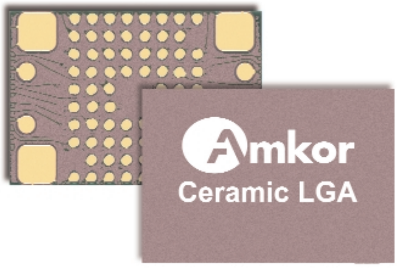
Applications:

Semiconductor technologies find enhanced performance by using the integrated design features of the CLGA package. Microprocessors / controllers, ASICs, Gate Arrays, memory, DSPs and PC chip sets find the CLGA family to be an ideal package. Applications requiring improved thermal performance and high-speed performance such as desk PCs, laptop PC's, and other similar products benefit from the CLGA attributes.

Features:

The CLGA offers a variety of feature. From innovative designs and expanding package offerings, Amkor provides a platform from prototype-to-production.

- Flexible land grid array lead counts
- Variety of body sizes
- 50 mil staggered & 100 mil matrix land grid pitch
- Heat plate / heat slug / heat sink
- Exceptional thermal and electrical performance by design
- Multi-layer, ground / power
- Cavity package



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